

Title (en)  
High-voltage insulation device

Title (de)  
Hochspannungsisolierungssystem

Title (fr)  
Système d'isolation à haute tension

Publication  
**EP 1150313 A3 20020529 (DE)**

Application  
**EP 01810288 A 20010321**

Priority  
DE 10020228 A 20000425

Abstract (en)  
[origin: EP1150313A2] The high voltage conductor (1) is cooled by a combination of a solid cooling material (2) and a liquid (3). The solid consists of a carrier material in the form of cellulose fibres impregnated with a suitable polymer matrix, epoxy resin. This is formed around the conductor in a vessel filled with a cooling liquid.

IPC 1-7  
**H01B 3/52**; H01B 3/54; H01F 6/06; H01F 27/32; H01B 12/00; H01B 3/40

IPC 8 full level  
**H01B 12/00** (2006.01); **H01B 12/16** (2006.01); **H01B 13/00** (2006.01); **H01F 6/04** (2006.01); **H01F 6/06** (2006.01)

CPC (source: EP US)  
**H01F 6/04** (2013.01 - EP US); **H01F 6/06** (2013.01 - EP US); **Y10S 336/01** (2013.01 - EP US)

Citation (search report)

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Designated contracting state (EPC)  
AT BE CH CY DE DK ES FI FR GB GR IE IT LI LU MC NL PT SE TR

DOCDB simple family (publication)  
**EP 1150313 A2 20011031**; **EP 1150313 A3 20020529**; **EP 1150313 B1 20080423**; AT E393456 T1 20080515; CA 2344771 A1 20011025; DE 10020228 A1 20011031; DE 50113876 D1 20080605; JP 2001357733 A 20011226; RU 2279727 C2 20060710; US 2001047879 A1 20011206; US 6791033 B2 20040914

DOCDB simple family (application)  
**EP 01810288 A 20010321**; AT 01810288 T 20010321; CA 2344771 A 20010420; DE 10020228 A 20000425; DE 50113876 T 20010321; JP 2001119185 A 20010418; RU 2001111395 A 20010424; US 84108201 A 20010425